

2N4066 (SILICON)

2N4067

DUAL P-CHANNEL MOS FIELD-EFFECT TRANSISTORS

Enhancement Mode MOS Field-Effect Transistors designed primarily for low-power, chopper or switching applications.

- High Forward Transadmittance –
 $|y_{fs}| = 2.5 \text{ mmhos (Min) @ } V_{DS} = -15 \text{ Vdc (2N4067)}$
- Low Forward Gate Current –
 $I_{GF} = 2.5 \text{ pAdc (Max) @ } V_{GS} = -25 \text{ Vdc}$
- Low Drain-Source "ON" Resistance –
 $r_{ds(on)} = 250 \text{ Ohms (Max) @ } V_{GS} = -15 \text{ Vdc (2N4067)}$

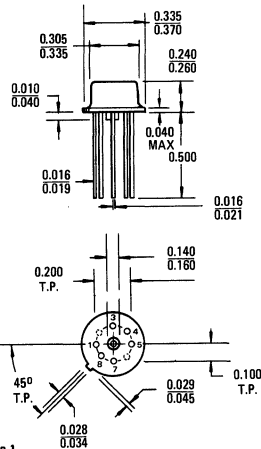
DUAL P-CHANNEL MOS FIELD-EFFECT TRANSISTORS



*MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-30	Vdc
Drain-Gate Voltage	V_{DG}	-25	Vdc
Reverse Gate-Source Voltage	V_{GSR}	+25	Vdc
Forward Gate-Source Voltage	V_{GSF}	-25	Vdc
Drain Current	I_D	200	mAdc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	0.6 4.0	Watt mW/ $^\circ\text{C}$
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	1.7 11.3	Watts mW/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +200	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-65 to +175	$^\circ\text{C}$

*Indicates JEDEC Registered Data.



- Pin 1. Drain 1
- 3. Gate 1
- 4. Substrate.
- 5. Gate 2
- 7. Drain 2
- 8. Source 1 and 2

Case 642-01

2N4066, 2N4067 (continued)

*ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Drain-Source Breakdown Voltage (I _D = 10 μAdc, V _{GS} = 0)	V _{(BR)DSS}	-30	—	Vdc
Source-Drain Breakdown Voltage (I _S = 10 μAdc, V _{GD} = 0)	V _{(BR)SDS}	-30	—	Vdc
Zero-Gate Voltage Source Current (V _{SD} = -15 Vdc, V _{GD} = 0) (V _{SD} = -15 Vdc, V _{GD} = 0, T _A = 150°C)	I _{SDS}	—	1.0 2.0	nAdc μAdc
Zero-Gate Voltage Drain Current (Note 1) (V _{DS} = -15 Vdc, V _{GS} = 0) (V _{DS} = -15 Vdc, V _{GS} = 0, T _A = 150°C)	I _{DSS}	—	1.0 2.0	nAdc μAdc

ON CHARACTERISTICS

Gate-Source Threshold Voltage (V _{DS} = -15 Vdc, I _D = 10 μAdc)	V _{GS(TH)}	-3.0	-6.0	Vdc
Forward Gate Current (V _{GS} = -25 Vdc, V _{DS} = 0)	I _{GF}	—	2.5	pAdc
"ON" Drain Current (V _{DS} = -15 Vdc, V _{GS} = -15 Vdc)	I _{D(on)}	10	50	mAdc

SMALL-SIGNAL CHARACTERISTICS

Static Drain-Source "ON" Resistance (V _{GS} = -15 Vdc, I _D = 0, f = 1.0 kHz)	r _{ds(on)}	—	500 250	Ohms
Forward Transadmittance (Note 1) (V _{DS} = -15 Vdc, V _{GS} = -15 Vdc, f = 1.0 kHz)	y _{fs}	1.5 2.5	—	mmhos
Output Admittance (V _{DS} = -15 Vdc, V _{GS} = -15 Vdc, f = 1.0 kHz)	y _{os}	—	300	μmhos
Input Capacitance (V _{DS} = -15 Vdc, V _{GS} = -15 Vdc, f = 1.0 MHz)	C _{iss}	—	7.0	pF
Reverse Transfer-Capacitance (V _{DS} = 0, V _{GS} = 0, f = 1.0 MHz)	C _{rss}	—	1.5	pF
Source-Substrate Capacitance (V _{DU} = -15 Vdc, V _{GS} = 0, I _S = 0, f = 1.0 MHz)	C _{SU}	—	5.0	pF
Drain-Substrate Capacitance (V _{SU} = -15 Vdc, V _{GS} = 0, I _S = 0, f = 1.0 MHz)	C _{DU}	—	5.0	pF

SWITCHING CHARACTERISTICS

Delay Time	(V _{DD} = -15 Vdc, I _{D(on)} = 10 mAdc, V _{GS(on)} = -15 Vdc, V _{GS(off)} = 0)	t _d	—	20	ns
Rise Time		t _r	—	30	ns
Turn-Off Time		t _{off}	—	50	ns

*Indicates JEDEC Registered Data.

Note 1: Pulse Test: Pulse Width ≤ 630 ms, Duty Cycle ≤ 10%.

FIGURE 1 — SWITCHING TIMES TEST CIRCUIT

